

## *Design Alternatives*

### Timing Scenarios (Clocking strategy)

- Master synchronized clock
- Source synchronous clocking
- Clock Recovery

### Basis for Signaling Circuit

- Voltage Mode vs. Current Mode
- Single sided vs. Single sided against reference vs. Differential

### Termination

- Source vs. Load vs. On-chip

### Direction

- Single direction vs. Bidirectional

### Data Representation

- Non Return to Zero vs. Return to Zero vs. Pulse vs. N of M Code (e.g. 8b/10b)
- Pulse Amplitude Modulation : PAM-2 (binary) vs. PAM-4 (4-level)

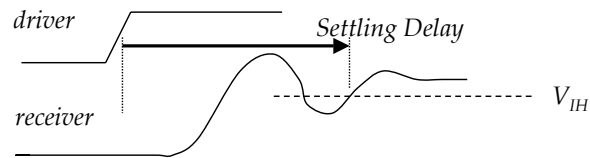
### Use of Channel Compensation

### Use of Error Correcting Codes

### Case Study - AC-Coupled Interconenct (ACI)

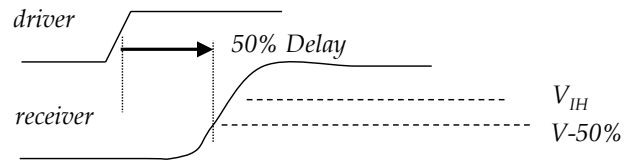
## Timing Scenarios

- Sufficient delay slack for noise to settle:



- ◆ If  $t_{interconnect-max} < 5 \times \text{line delay}$ , then design is very simple.

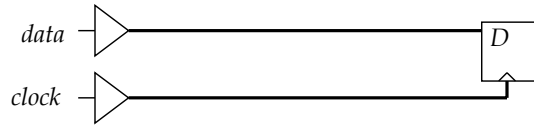
- First Incident Switching:



## ...Timing Scenarios

### Source-Synchronous Switching

- Send clock with data
  - ◆ (or recover clock from data)



- In such systems, the rise-times and skew from inter-symbol noise, processing and temperature variations determines maximum signal speeds

E.g. 1 Gbps, 30 inch wire

$t_{\text{symbol}} =$

$t_{\text{wire}} =$

If clock jitter has to be less than 10% of  $t_{\text{symbol}}$ ,  $t_{\text{jitter}} =$

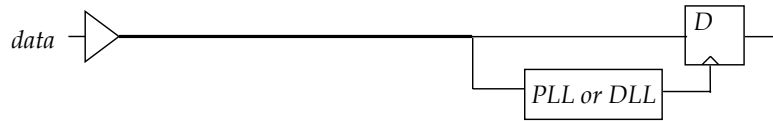
What % variation in clock " $t_{\text{wire}}$ " would be acceptable?

If a via  $C_L = 1$  pF,  $Z_0 = 50$  Ohm, what is the  $\tau$  of a via?

## ... Timing Scenarios

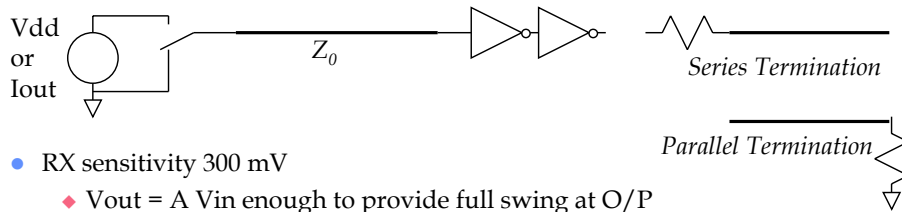
### Clock & Data Recovery

- Recover clock from the data so that delay does not need to be precisely controlled.



- Issues:
  - Ensuring enough edges in data signal to generate clock
  - Design of clock recovery circuit (Phase Locked Loop, Delay Locked Loop)

### Voltage vs. Current Signalling



- RX sensitivity 300 mV
  - ◆  $V_{out} = A V_{in}$  enough to provide full swing at O/P
- Energy per transition,  $E_{sw} = \Delta V^2 t_{line} / Z_0 = \Delta I^2 t_{line} Z_0$

Comparison: (Ignore lines losses)

Voltage Mode, Series Termination

Voltage Mode, Parallel Termination

## Voltage vs. Current Mode

(ie. Portion of constant current source fed onto line)

Current Mode, series termination

- Requires current-mode RX (I.e. Low input impedance)

Current mode, parallel termination

- Line swing and power:

$$V_{sw} = Z_0 I_{out} \quad E_{sw} = I_{sw}^2 t_{line} Z_0$$

- RX swing

$$V_{sw} = R_{term} I_{out}$$

*In a 50 Ohm system, 300 mV requires  $I_{out} = 6 \text{ mA}$*

Sample Comparison (1 ns line)

Voltage mode, 3.3 V, series term

Current mode, 10 mA, parallel term

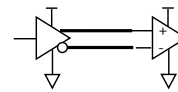
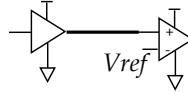
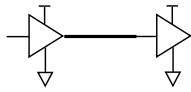
E<sub>sw</sub>:

### Single sided vs. Differential

Cost:

- Full differential doubles board real-estate, and pin-count

Performance



Sensitivity:      Smallest RX input to give full swing at output (limited by gain A)

Noise:

TX:

RX:

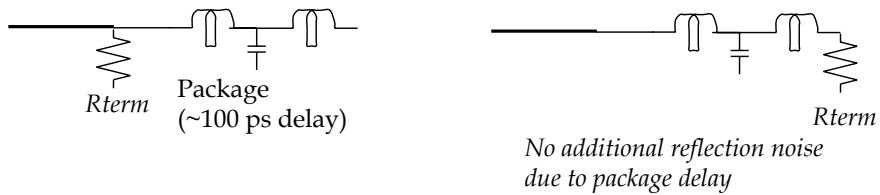
## Termination

### Parallel vs. Series

- See above

### Off-chip vs. On-chip

- High-speed requires on-chip

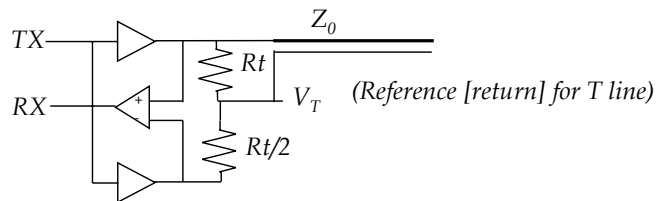


- How?
  - ◆ See earlier slides on resistive load
  - ◆ Common approach: Use trimming resistors and measure against an off-chip comparison

## BiDirectional Signalling

Halves number of wires and pins!

Current Mode:



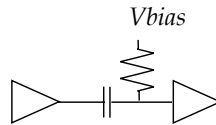
- Estimates  $V_{\text{transmit}}$  from TX and subtracts it from signal at pin
- Speed limited compared with single sided as estimate is imperfect (due to package,  $R_{\text{term}}$  mismatch, etc.) and ISI tends to be larger
- Voltage mode and differential versions

## Signal Coding

- Run length constrained and DC balanced codes
- Error Correction Coding
  - Not used much today but likely in future
- Pulse Amplitude Modulation (PAM), NRZ vs. RZ

### Reasons to constrain max # and ratio of 1's or 0's

- AC Coupled Signals



*Want : Fixed Vbias*

→ *Average value of input signal must be known*

→ *Known ratio of 0's to 1's*

→ *AC balanced signals*

- Provide sufficient edges for clock recovery
  - ♦ → Max # of 1's or 0's in sequence known
- Reduce SSN, return current and  $d/dt$ (return current)
  - ♦ → Balance 01 and 10 simultaneous transitions in a bus

## Concepts in Balanced Codes

### Run Length

- Max # of 1's in sequence =  $r_{max}$
- Min # of 1's in sequence =  $r_{min}$
- Code referred to as  $(r_{min}-1, r_{max}-1)$  code

### Bit Stuffing

- Simplest way to achieve a  $(0,m)$  code is to insert a false bit when  $r_{max}$  hit
- Requires synchronization at frame level and counters at RX and TX
- E.g. Achieving  $(0,2)$ 
  - ◆ Data : 01000011110
  - ◆ Encoded data: 01000101111010
- Though reduces low frequency content, does not eliminate a DC bias drift
- Can not predict actual symbol rate
  - ◆ Can predict worst case symbol rate
    - What is it for  $(0,2)$ ?

*... Concepts*

## Disparity

- = # of 1's - # of 0's

## Digital-Sum Variation (DSV)

- = Max. variation in disparity
- Constant DSV → DC-balanced signal,  $r_{max} = DSV$
- Determines low frequency components of signal

## Block Codes

### Nonoverlapping Block Codes

- Each block of  $n$  bits is coded as  $m$  bits with equal numbers of 1s and 0s
- Number of zero-disparity code words in  $m$  bits is  $\binom{m}{n/2}$
- Number of input signals is  $2^n$
- Thus code exists if  $\binom{m}{n/2} > 2^n$
- Code efficiency =  $n/m$

- E.g.  $n=2, m=4$ 

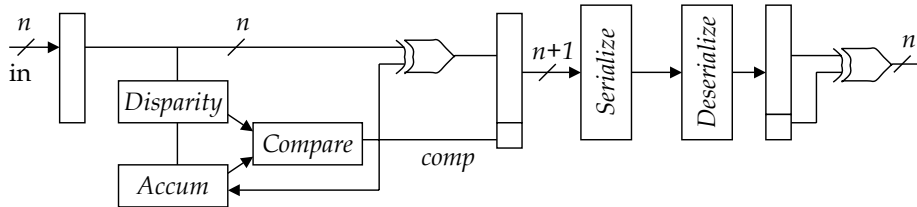
<u>input</u>	<u>code</u>
00	0101
01	1010
11	1100
10	0011

Efficiency = 50%

- E.g.  $n = 8, m=12$ , efficiency = 67%

## Running Disparity Codes

- Permits non-zero disparity in “code word”
- Constrains worst case disparity



- Disparity = disparity of current block
- Accum = accumulated disparity, including comp bit
- Compare = 1 if Disparity and Accum have same signs  
=  $\sim(\text{sign}(\text{accum}))$  if disparity = 0
- Max run length =  $2(n+1)$ ; Disparity ranges over  $[-3n/2, 3n/2]$
- DSV =  $3n$
- 8-bit burst error occurs whenever comp bit wrong

## *Spatial N of M Signalling*

Used to reduce Common Mode noise in power/ground/return system

- Reduces SSN at TX
- Reduces signal return current
- e.g. Hamming Codes

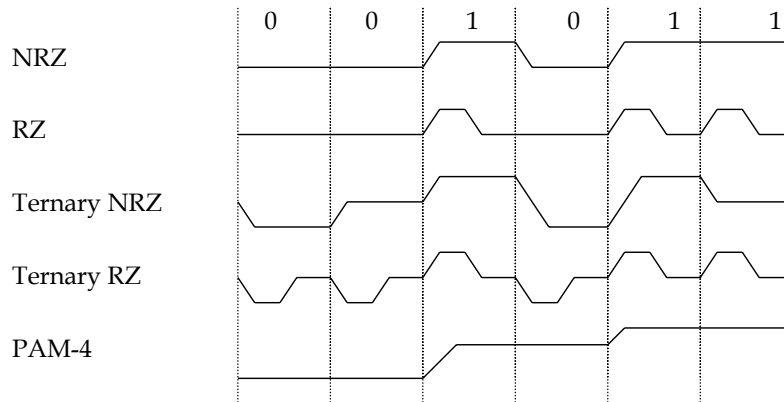
### Single Symbol Encoding

NRZ = Non Return to Zero

RZ = Return to Zero

Ternary → 3 level signaling

PAM-4 → Encode bit pair (symbol) as one of 4 levels



## Symbol Encoding Tradeoffs

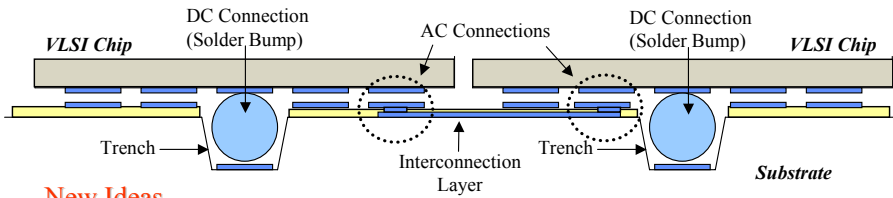
- NRZ (also called PAM-2)
  - Most common
- RZ
  - Requires 2\* channel bandwidth of NRZ
  - (Only used in optical signals where BW is almost infinite)
- Ternary NRZ
  - Use against Vref in single-sided TX, differential RX
- Ternary RZ
  - DC balanced
  - Use against Vref in single-sided TX, differential RX
- PAM-4
  - Requires half channel BW of PAM-2
  - Reduced signal swing per symbol
  - Requires ADC at RX
  - Not useful unless channel BW very limited

## Case Study

### AC Coupled Interconnect

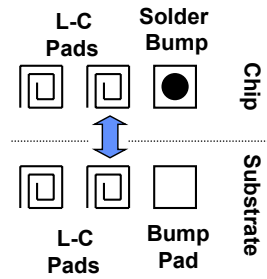
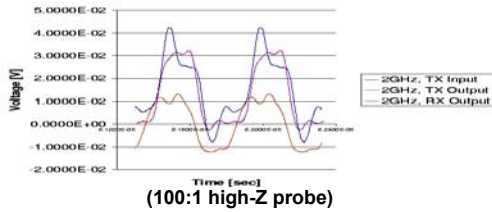
- NCSU Research Project
- Coding issues
- Eye evaluation
- Outline
  - ◆ Overview
  - ◆ Benefits
  - ◆ System view
  - ◆ Circuits
  - ◆ Eye Diagram analysis

**AC Coupled Interconnect Concept**



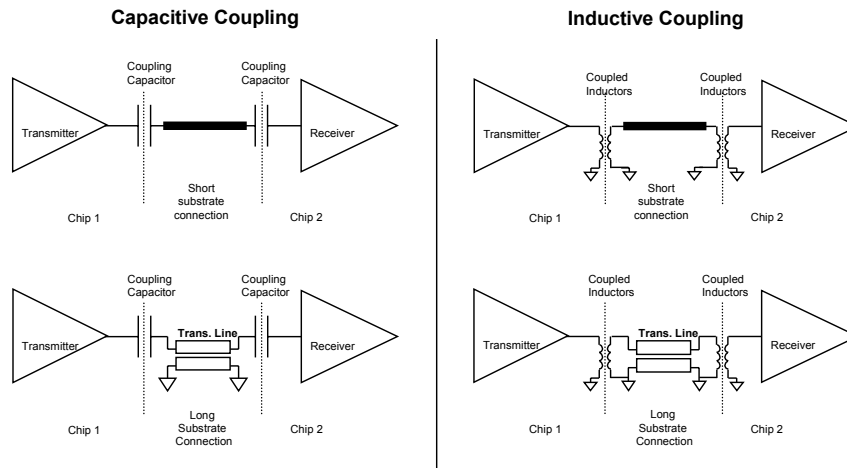
**New Ideas**

- AC coupled connections down to 70  $\mu\text{m}$  pitch
- Short- or long-range capacitive or inductive coupling
- Buried solder bumps to bring chips into proximity
- High-speed, low-power current switching techniques



1. Want to AC couple signals but maintain DC connections
2. Need AC pads close to substrate
3. Buried solder bumps enable both
4. Inductive or Capacitive coupling

## Basic Circuit Models



Driver is simple cascaded inverter stage

Center pad chip1 to center pad chip2 ->  $C_{couple}=21\text{fF}$

pad to pad parasitic ->  $C_{parasitic}=2.4\text{fF}$

pad to chip ground ->  $C_{shunt}=2.5\text{fF}$

This assumes no metal underneath the pads

Chip to Chip spacing is zero, but pad to pad spacing is  $3.4\mu\text{m}$

- this is due to the thickness of each chip's passivation layers

## *Benefits of ACI*

### Dense I/O

- e.g. 800 power/ground, 6,000 signal per.sq.cm.
- Achieve end of the ITRS today!
- Can be applied to dense connectors too

### Low power

- 20% Transmit power of conventional interconnect

### High Speed

- Will extend high speed SerDes

### Robust

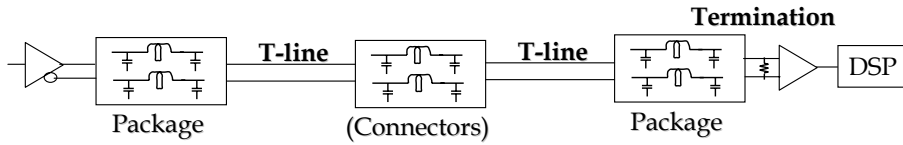
- Can achieve low Bit Error Rates

### Manufacturable

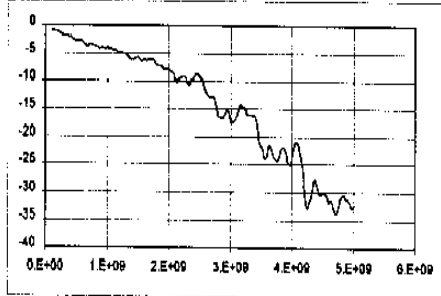
- Conformable
- No change to base fabrication process and materials

### System View of Conventional I/O

Typical : ~3 Gbps, 100 mW/channel link



**Lossy Channel:**



**DSP to sharpen edge response:**

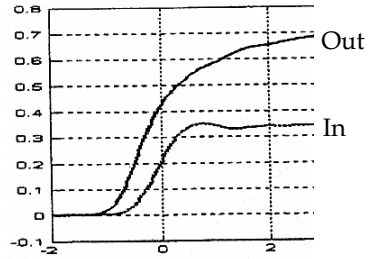


Figure 3 – Typical S21, transmission plot for serial link and picture of what is happening in the frequency domain.

## *Conventional I/O*

1 V in, 50-100 mV needed at RX

- Losses < 23 dB required

Low-pass filter

- Makes 10 Gbps, 20 Gbps etc. increasingly difficult

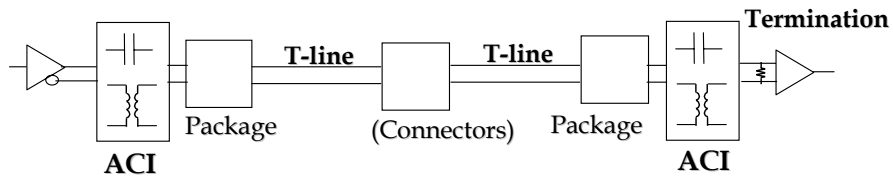
Energy per bit

- $E = \Delta V^2 t / Z_0 + \text{overhead for circuits \& DSP}$
- Increased by differential, analog DSP at RX

Pin-in-hole connectors

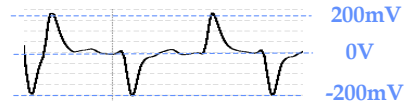
- Creates dense via field
  - ◆ Disrupts return current
  - ◆ Increases high frequency losses

## ACI



▷ **ACI acts as a differentiator:**

- ◆ Pulse signaling
- ◆ Energy per bit reduced
- ◆ Integrate at Receiver



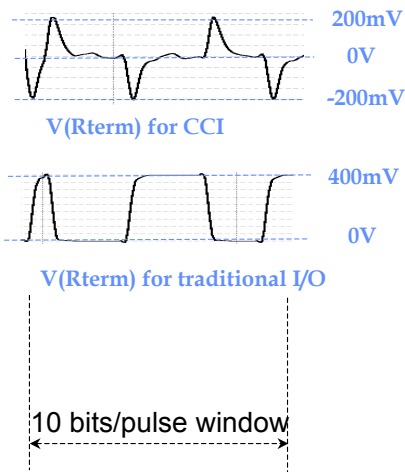
▷ **ACI acts as a high-pass filter**

- ◆ Compensate for line losses
- ◆ Extends useful frequency range
- ◆ Potentially avoids DSP

▷ **ACI transformers can be asymmetric**

- ◆ Can accept higher line losses

*Why 80% less power dissipation?*



Suppose  $V_{pp}=0.4v$ ,  $R=50ohm$ , 6Gbps

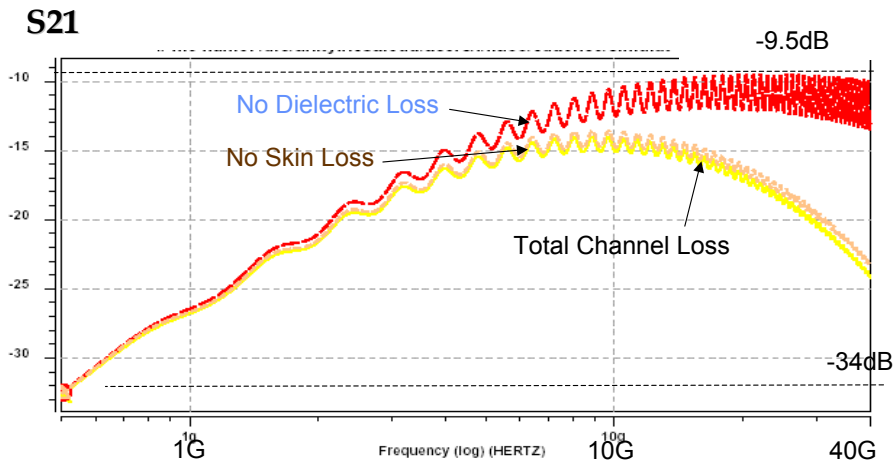
For CCI: Power of each pulse is less than  $(0.5*(0.2)^2/50)=0.4mw$ , totally 5 pulses in period of 10 pulse window, so average power is 0.2mW

For Traditional: Power of each '1' bit is  $(0.4)^2/50=3.2mW$ , totally 5 '1' bit in period of 10 bit window, so average power is 1.6W

$0.2/1.6=0.125$ , that is 87.5% less power

For lower frequency switching, even more power saving

[<< Back](#)

*CCI Channel Response1*

CCI channel response for 10cm, 50ohm TL  
Dielectric Loss become more important for High Frequency

Signal Source : 1 V-----Yes

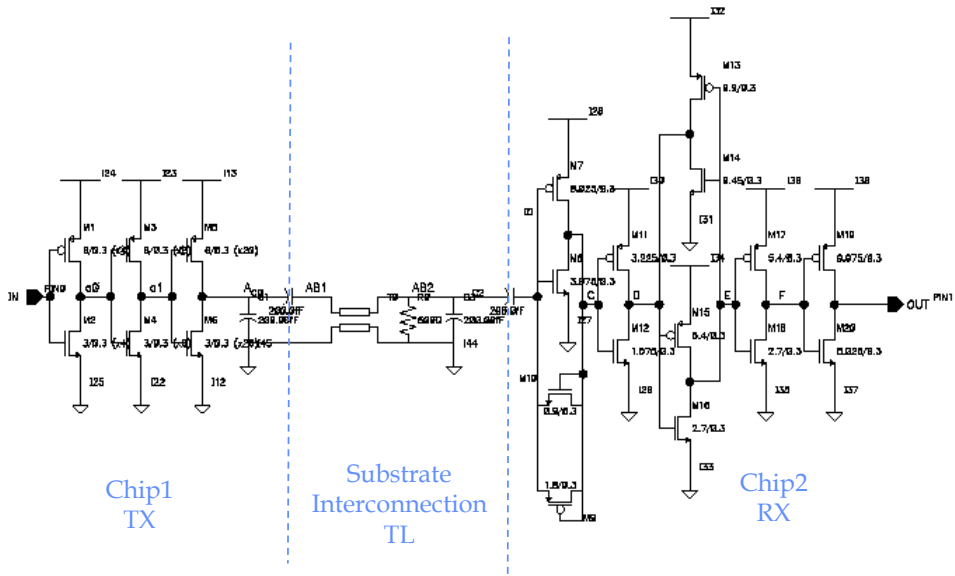
Get into dB too., 9 dB at 1 GHz. -----Now in dB, but why 9 dB at 1GHz????

REDO to just channel response w/ - termination artificialities (LL)-----I am simulating what exactly in my design( no termination at RX side, so there is ripples) See backup slides: Wondering: Use Channel\_out/IN or Channel\_out/Channel\_in???

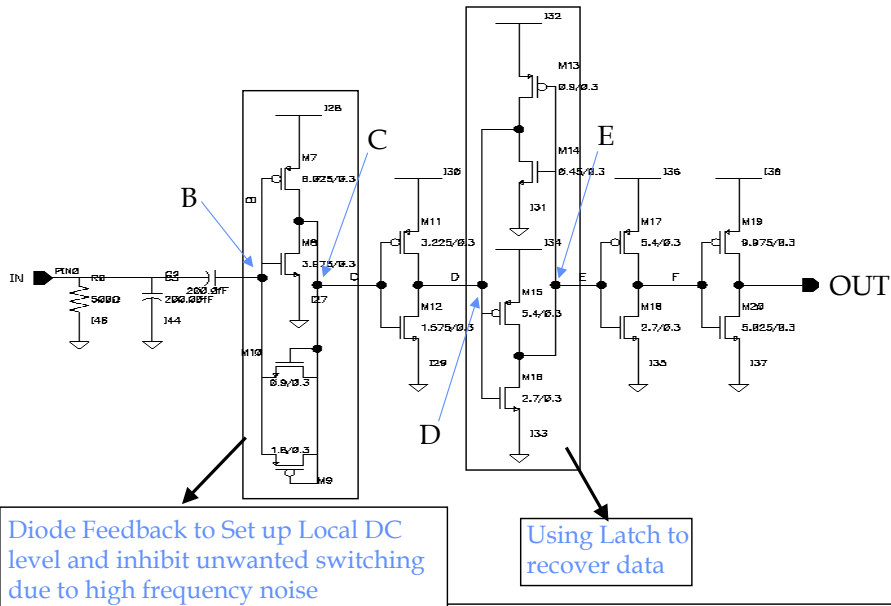
Include sketch of ckt (LL).-----See backup slides

Include measured S12 for capacitor (KC) (or see TEAM report)—included, see next slide

# CCI Circuit Schematic



# Kühn's Receiver



Always high gain.-----added in next slide

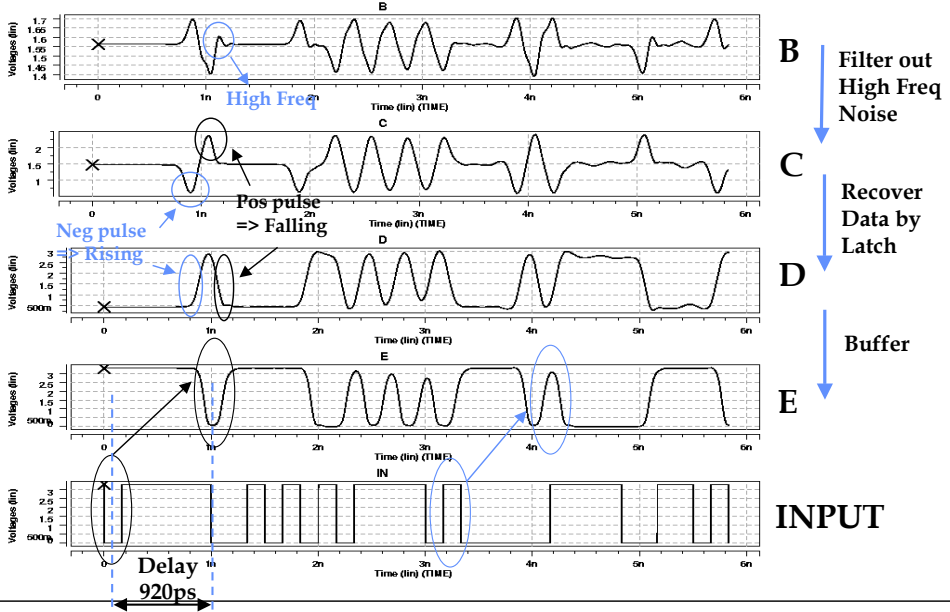
Always high Zin? Cm??----see next slide

Noise filter like calmp diode.-----see next slide

Look at frequency response and DC response.-----next slide

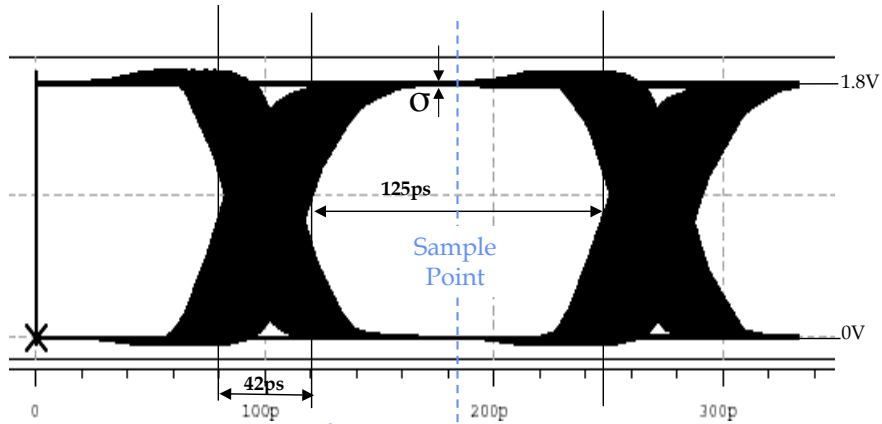
What does eye look like at input and why is it opening up?

*How Kühn's RX Works?*



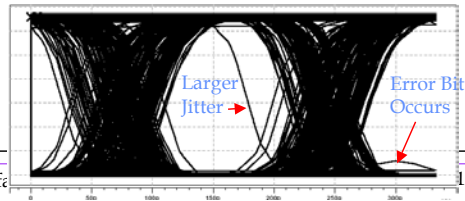
Not really high freq. noise?—see previous slide

### EYE Diagram Analysis



4b/5b Coding

5b/6b Coding



Use this signal for CDR, not input voltage.-----mentioned in slide18

## Codes Evaluated

### 4B5B coding

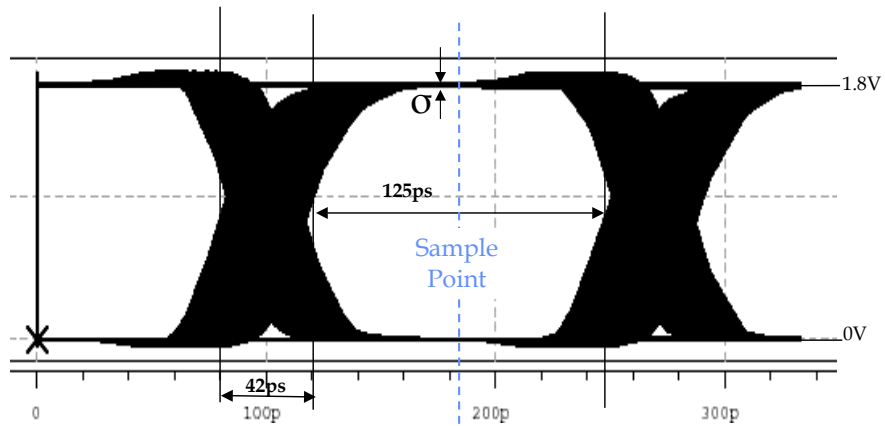
Input word	Output word
0000	11110
0001	01001
0010	10100
0011	10101
0100	01010
0101	01011
0110	01110
0111	01111
1000	10010
1001	10011
1010	10110
1011	10111
1100	11010
1101	11011
1110	11100
1111	11101

### 5B6B coding

Input word	Output word
00000	101011
00001	101010
00010	101001
00011	111000
...	...
11100	010011
11101	010111
11110	011011
11111	011100

*Block versions.*

*Above, actually used a "running" version.*

*EYE Diagram Analysis*

**Highest data rate** is determined by Jitter and Rising/Falling edge.

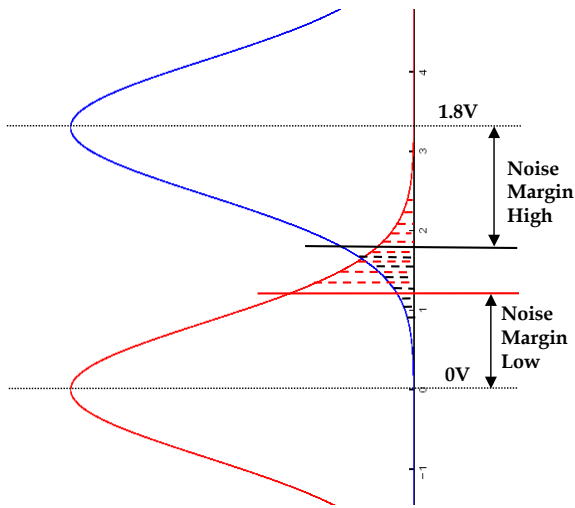
**Jitter**: Caused by ISI, from both coupling cap and Kuhn's Rx.

**Rising & Falling Edge**: Determined by Vdd, Device (R & C).

**BER**: Determined by EYE Opening, jitter of sample clock.

Use this signal for CDR, not input voltage.-----mentioned in slide18

*Estimate BER by EYE*



Note: Here we assume the signal is gauss distributed.

BER is expressed here by the shadow area:

Blue shadow for BER of '1'  
Red shadow for BER of '0'

**BER=Integration of the shadow area**

$$BER = \int_{NMH}^{\infty} \frac{1}{\sigma_1 \sqrt{2\pi}} \cdot \exp\left(-\frac{x^2}{2\sigma_1^2}\right) dx + \int_{NML}^{\infty} \frac{1}{\sigma_0 \sqrt{2\pi}} \cdot \exp\left(-\frac{x^2}{2\sigma_0^2}\right) dx$$

$$= \frac{1}{2} \operatorname{erfc}\left(\frac{NMH}{\sqrt{2}\sigma_1}\right) + \frac{1}{2} \operatorname{erfc}\left(\frac{NML}{\sqrt{2}\sigma_0}\right)$$

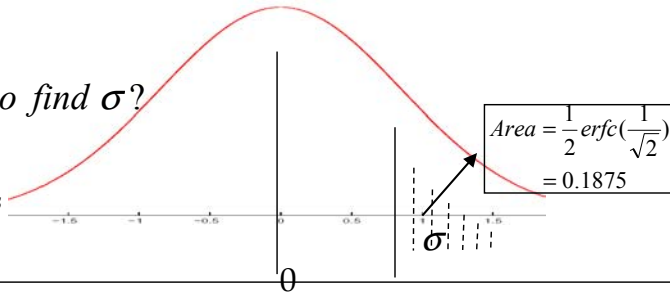
if  $\sigma_0 = \sigma_1 = \sigma$ ,  $NMH = NML = 0.6V$ ,

$$BER = \operatorname{erfc}\left(\frac{NM}{\sqrt{2}\sigma}\right) \leq 10^{-12} \Leftrightarrow \sigma = \frac{NM}{7} \leq 0.085V$$

$$BER = \operatorname{erfc}\left(\frac{NM}{\sqrt{2}\sigma}\right) \leq 10^{-17} \Leftrightarrow \sigma = \frac{NM}{8.6} \leq 0.07V$$

How to find  $\sigma$ ?

Note: Here we assume the signal is gauss distributed.



Redo to get 10-17. What NM gives 10-17??----added

Schmidt Trigger RX.-----what do you mean?????

### *Summary*

What are the main factor(s) that cause eye closure?

How is equalization useful?

How are current mode and voltage mode signalling different?

What are the advantages of single-sided TX, differential RX over single-sided RX?

*... Summary*

What is the advantage of a full differential system?

What are the uses of DC-balanced and run-length codes?

What is the potential advantage of PAM-4 over PAM-2?